

DuPont™ CuSolve™

Copper Compatible Removers

Optimized to Selectively Remove Post-Etch Residues

Product Description

DuPont™ CuSolve™ copper compatible removers are designed to remove post-etch residue. They perform well in a variety of equipment including single-wafer and batch spray platforms.

Features

- Formulated for optimum compatibility with copper substrates
- Compatible with single-wafer type clean equipment
- Compatible with batch spray type clean equipment
- Aqueous-based formulation
- No post-clean rinse required other than water
- Operates well below the flashpoint of the solution
- Low evaporation rate at operating temperature
- Low viscosity
- High flashpoint
- No banned or reportable chemical components
- Copper oxide removal time <30 seconds at 25 °C
- Compatible with a variety of Low-k films
- Bathlife >48 hours
- Lower cost of ownership than competitive products

Benefits

- Improved yields in copper processing
- Offers flexibility in equipment choice
- Greater device reliability and product yields
- Helps reduce environmental, health and safety concerns
- Provides a safer chemical process
- Long bath life, low air emissions, low factory operating cost
- Ease of operation of tool and chemical supply equipment

Figure 1. Before Clean

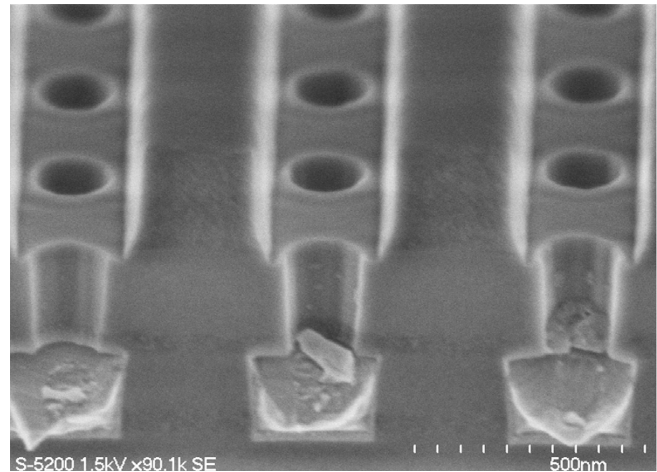


Figure 2. After Clean with DuPont™ CuSolve™ Copper Compatible Remover

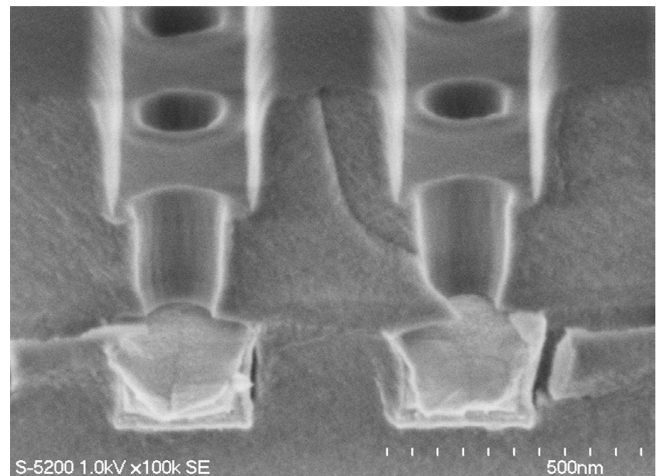
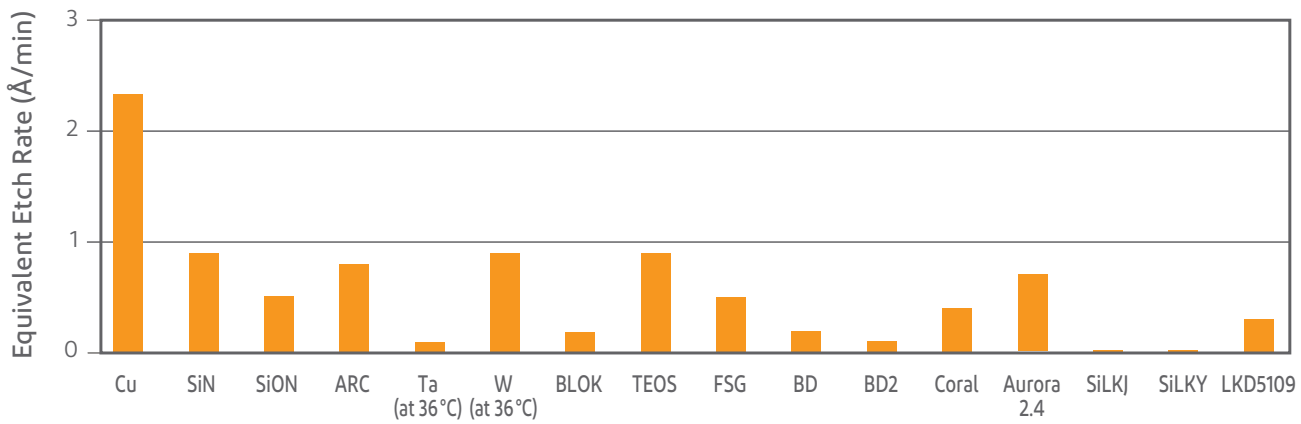


Figure 3. Materials Compatibility (total loss in 10 minutes at 25 °C)



Substrates were exposed to DuPont™ CuSolve™ EKC520™ at 25 °C for 10 minutes. Etch rates were calculated.



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For more information on DuPont™ CuSolve™ or other DuPont products, please visit our website.

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